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- (71) Applicant (for all designated States except US): **MAT-SUSHITA ELECTRIC INDUSTRIAL CO., LTD.**  
[JP/JP]; 1006, Oaza Kadoma, Kadoma-shi, Osaka 5718501 (JP).

(74) Agents: **IWAHASHI, Fumio** et al.; c/o Matsushita Electric Industrial Co., Ltd., 1006, Oaza Kadoma, Kadoma-shi, Osaka 5718501 (JP).

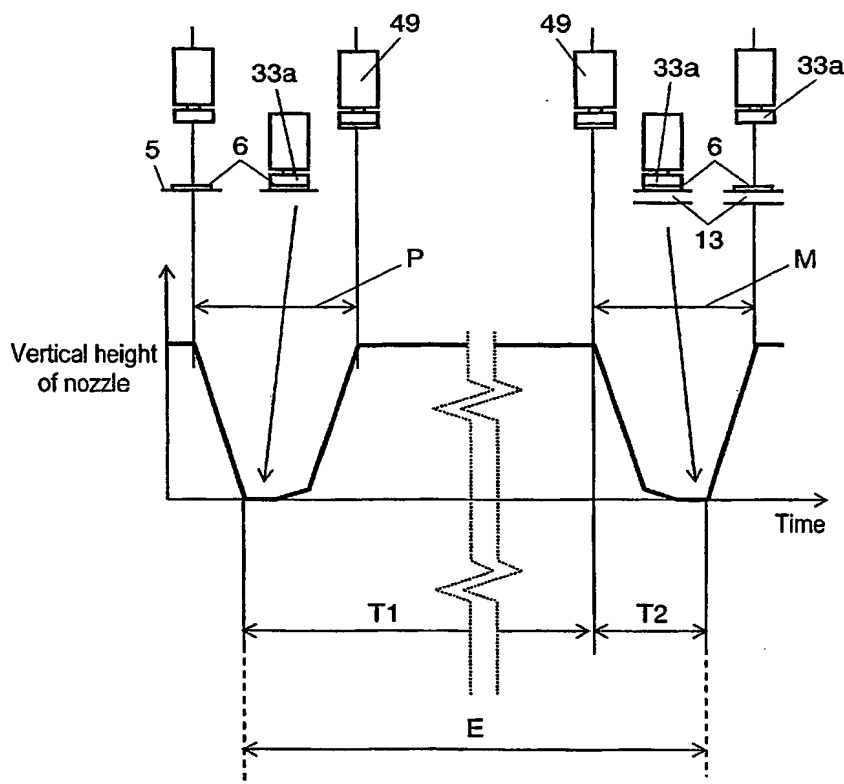
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- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **HAJI, Hiroshi**,  
**OZONO, Mitsuru**.

[Continued on next page]

(54) Title: **ELECTRONIC COMPONENT MOUNTING APPARATUS AND METHOD OF MOUNTING ELECTRONIC COMPONENTS**



(57) Abstract: In an electronic component mounting process for mounting electronic components (6) to a substrate (13), each of the electronic components (6) having an adhesive layer on a surface to be bonded to the substrate (13) is picked up with suction nozzle (33a) provided with individual heater (49), and a time taken for the mounting operation is so allotted that a first heating time (T1) of a duration from a moment when the suction nozzle (33a) comes into contact with the electronic component (6) for picking it up till another moment immediately before it begins a mounting motion to the substrate (13) is longer than a second heating time (T2) of a duration from the moment when the suction nozzle (33a) begins the mounting motion till another moment when it leaves the electronic component (6) mounted to the substrate (13).



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